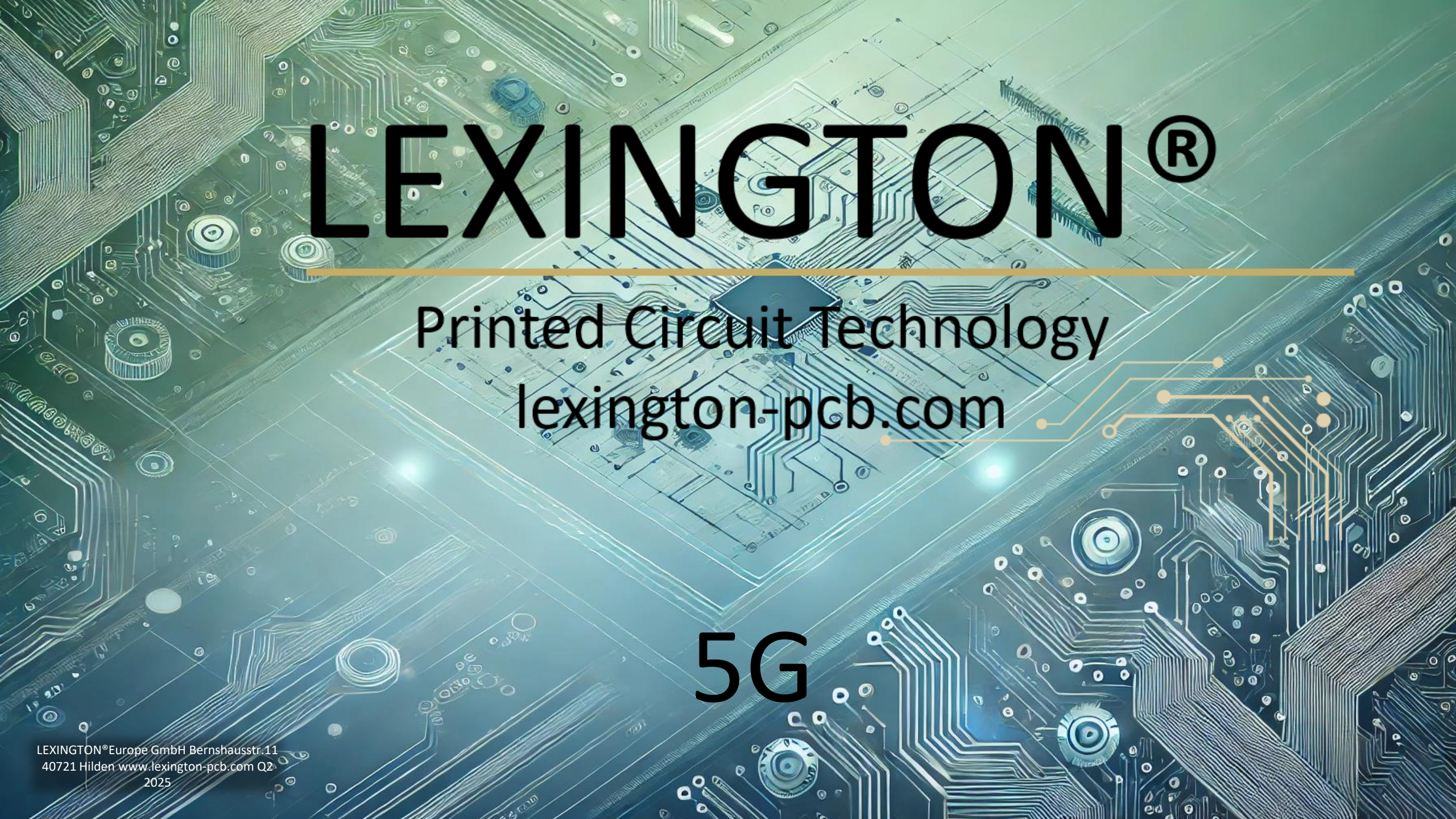


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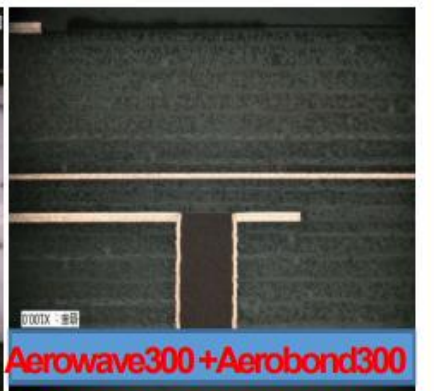
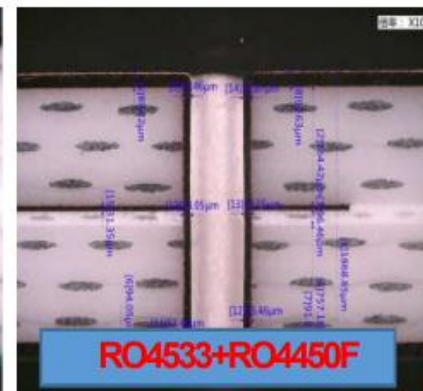
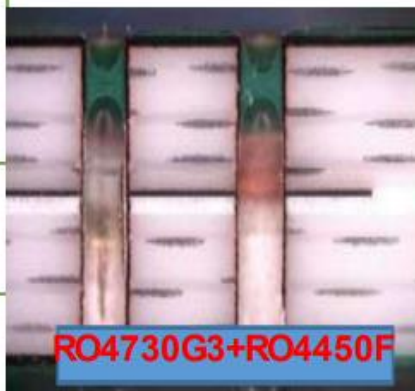
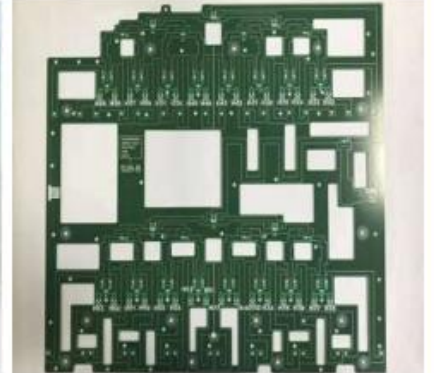
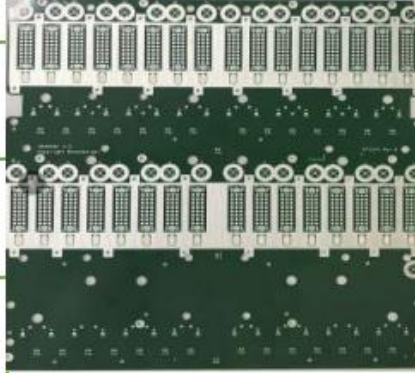
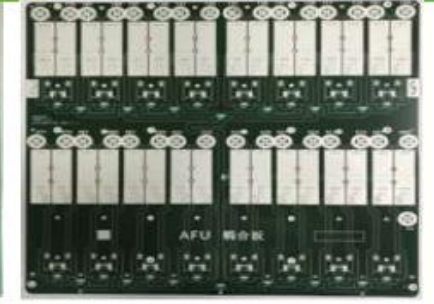
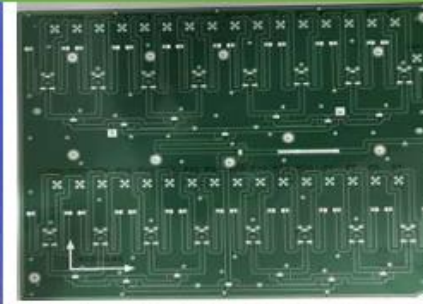
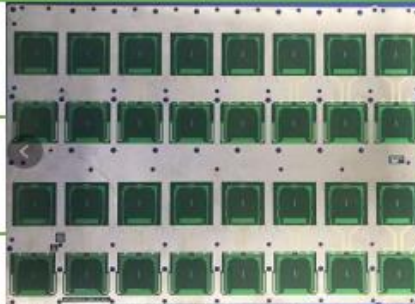


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5G

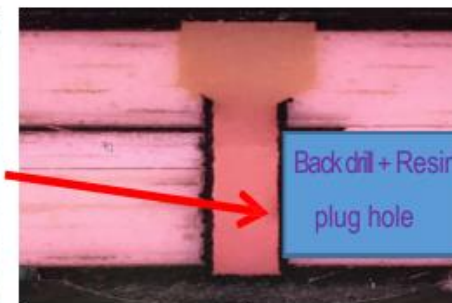
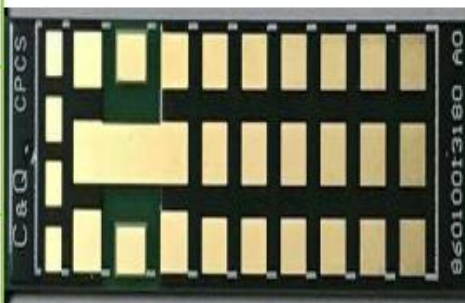
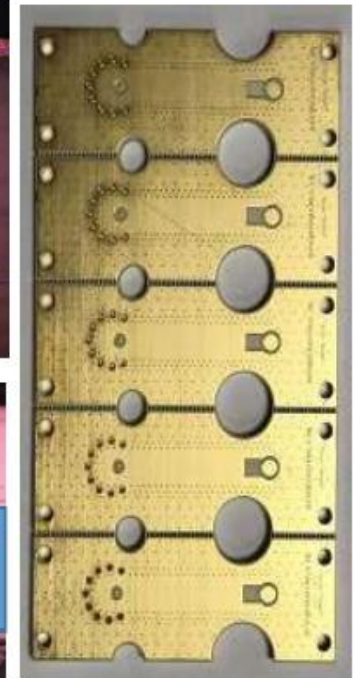
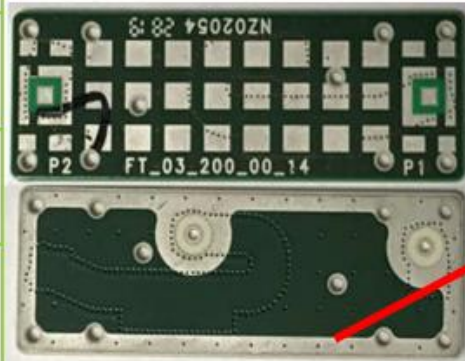
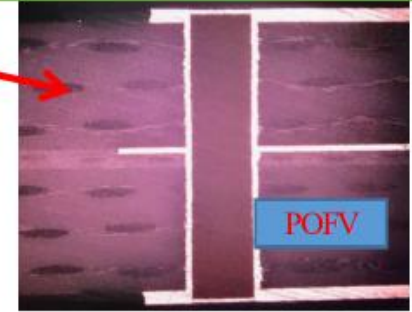
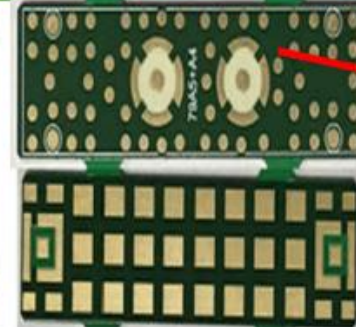
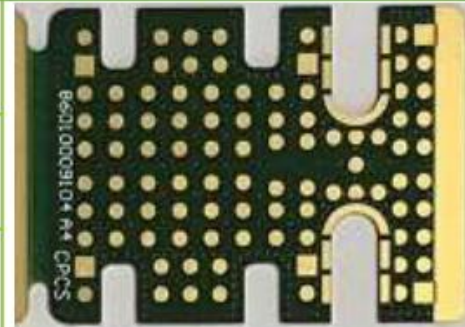
Antenna

Items	Capability			
Layers	2L~ 6L			
Dimension	200mm ~ 750 mm			
Board Thickness	0.2mm ~ 3.2 mm			
Surface finishing	Chem Tin, Chem Gold			
Material	RO4730G3; Aerowave300 RO4730G3+RO4450F RO4533+RO4450F Aerowave300 + Aerobond300 Aerowave300 + S6B			
Special Design	Back drill, Blind via,POFV, Cavity			
Application	5G Base Station			



Filters PCB

Items	Capability
Layers	2~6L
Dimension	22X42~ 130X170mm
Board Thickness	0.90m ~ 2.90 mm
Surface finishing	Chem Tin, Chem Gold
Material	RO4730G3/RO4350B/S7135/ S71 36 S7135/S7136+FR4 PTFE+Aerobond300
Special Design	Mixed pressing, Back drill, Blind via,POFV, Half hole metalization
Application	5G Base Station, Communication



Optical Module PCB

Items	Capability
Impedance	$\geq 100 \text{ ohm} \pm 8\%$
	$\leq 50 \text{ ohm} \pm 10\%$
Material	M4, M6, TU-933+ EM890K, EM888, TU-883, TU872 SLK
Special Design	Mixed pressing, Back drill, Blind via, Burried via, POFV, Copper filled, Depth control drill
Min. Finger Pitch	4+/-2 mil
Board edge to finger edge distance	10mil
Middle of finger to board edge	+/-4 mil
Finger width tolerance	+/-1 mil
Finger length tolerance	+/-2 mil
Bonding pads distance	$\geq 4 \text{ mil}$



QSFP+



**QSFP-28
Buried Copper**



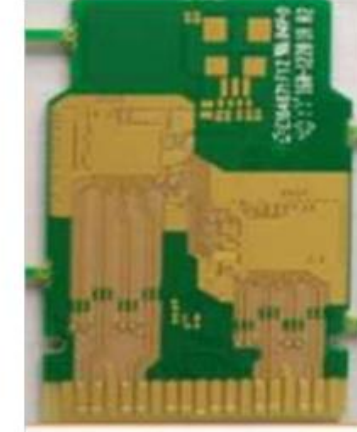
CFP4



SAS 4.0



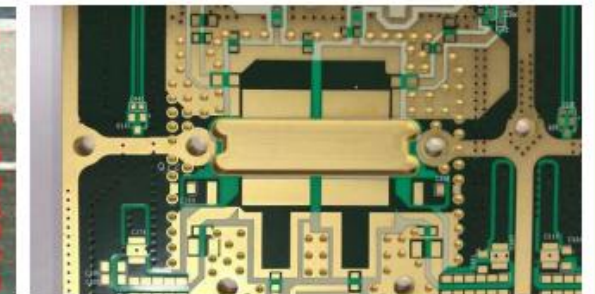
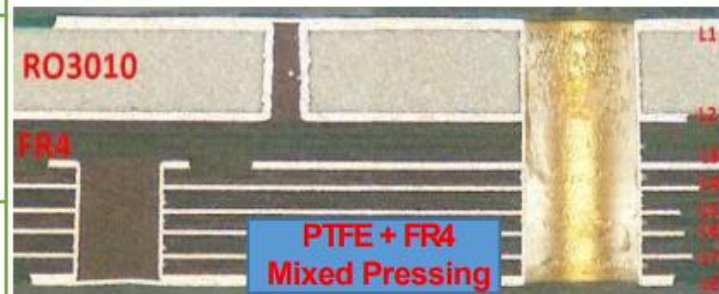
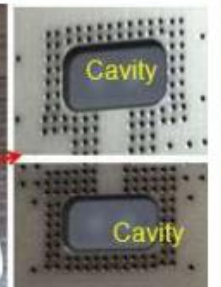
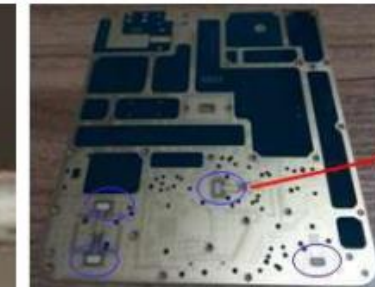
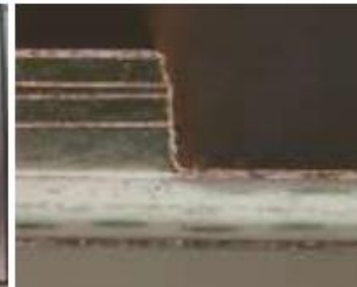
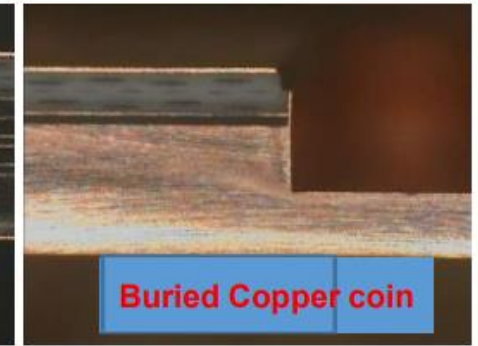
**QSFP-28
Buried Copper Coin**



**QSFP-28
Buried Copper Coin**

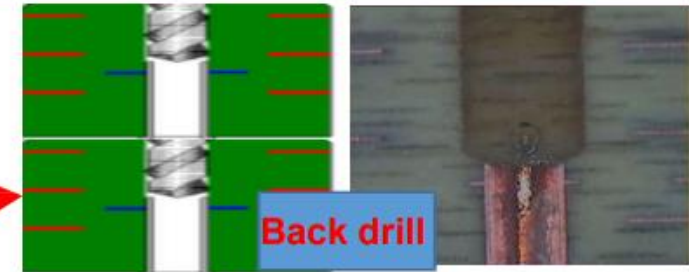
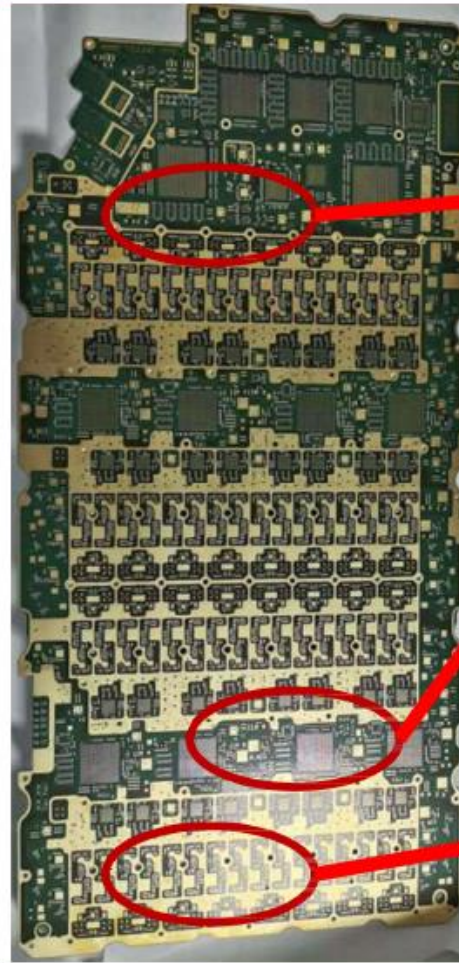
RF / Power Amplifier PCB

Items	Capability			
Layers	20L+			
Dimension	457 × 610mm			
Board Thickness	0.5m ~ 4.0 mm			
Surface finishing	Chem Tin, Chem Gold			
Material	PTFE+FR4 RO4350B+FR4			
Special Design	Buried copper coin(flatness $\pm 0.05\text{mm}$); Mixed Pressing; Cavity			
Application	Base Station, Communication			



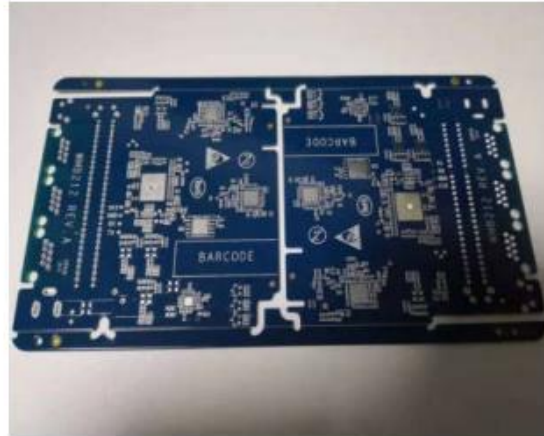
5G AAU/TRX PCB

Items	Capability
Layers	20L+
Dimension	450 × 850mm
Board Thickness	3.1mm
Surface finishing	Chem Gold
Material	High Speed material
Special Design	Buried Copper Coin : 64 pcs Back drill
Application	Base Station, Communication

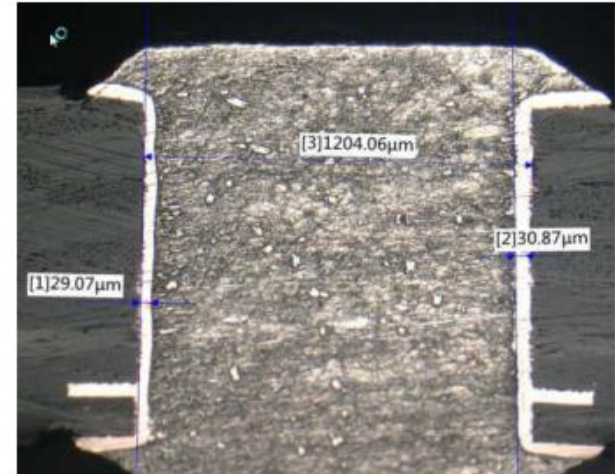


Small base Station PCB

Items	Capability
Layers	4-12 Layers
Dimension	100 × 200mm
Board Thickness	0.5-2.6mm
Surface finishing	Chem Gold, LF HASL
Material	RO4350B, S7136H, FR4
Special Design	Impedance control Aspect ratio 14:1 0.2mm Hole diameter
Application	Base Station, Communication



最终厚度 mil	减铜率	层别	理论厚度 mil	物料名称
0.7		Leg1		Legend
1.82	62%	SM1	0.7	Solder Mask
4.01		L1	0.6	NOZ
1.2	59%	L2	4.5	S0401 2116RC50
24			1.2	10Z
1.2	59%	L3	24	S1141 24mil
4.01			1.2	10Z
1.82	64%	L4	4.5	S0401 2116RC50
0.7		SM4	0.6	NOZ
		Leg1	0.7	Solder Mask
				Legend



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